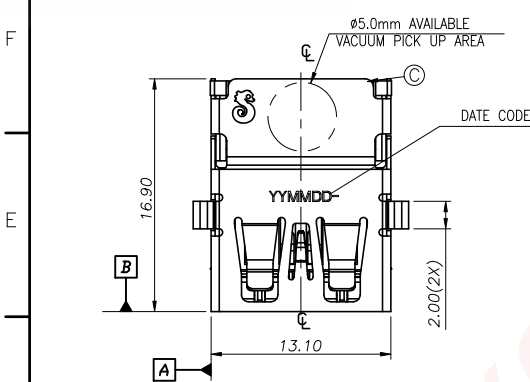
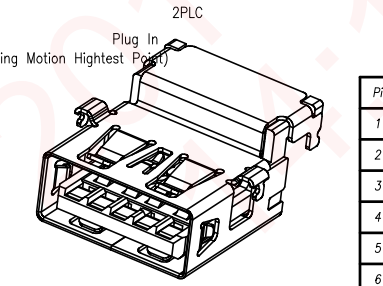
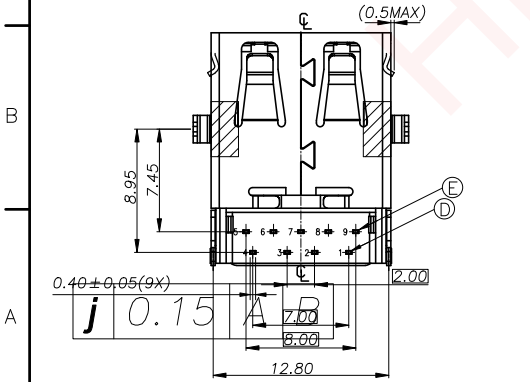
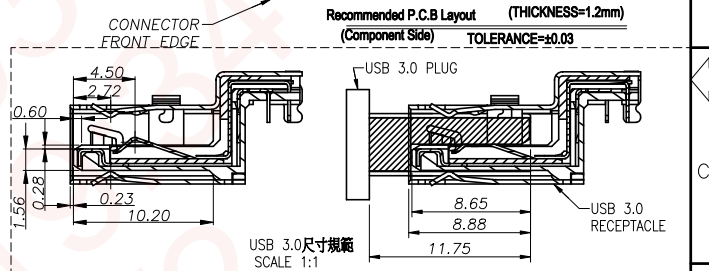
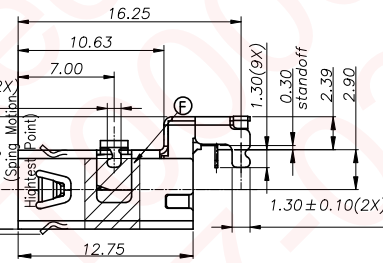
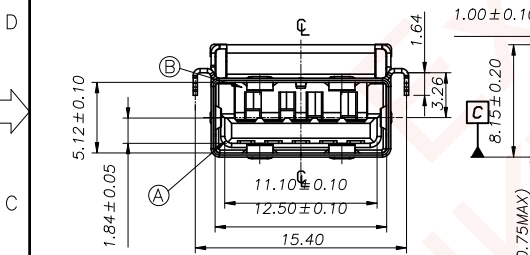
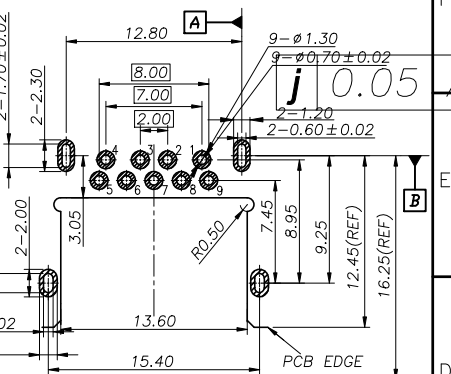


1 2 3 4 5 6 7 8

| REV. | ECN NO OR DESCRIPTION | REVISED | DATE |
|------|-----------------------|---------|------------|
| A | PDR NO:T160809-1A | ALLEN | 2017.02.17 |



- SPECIFICATIONS:**
- ELECTRICAL CHARACTERISTICS:**
 - CURRENT RATING: 1.8A (PIN1,4) ; OTHER CONTACTS 0.25A
 - CONTACT RESISTANCE: 30mΩ MAX.
 - DIELECTRIC WITHSTANDING VOLTAGE: 100V AC FOR 1 MINUTE
 - INSULATION RESISTANCE: 100MΩ MIN
 - MECHANICAL CHARACTERISTICS:**
 - INSERTION FORCE : 3.0 Kgf MAX
 - WITHDRAWAL FORCE : 1.0~3.0 Kgf MIN(INITIAL),0.8 Kgf MIN(AFTER TEST)
 - DURABILITY: 5,000 CYCLES.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE IDENTIFICATION MARK ON JACK: Ⓞ
 - HALOGEN FREE IDENTIFICATION LABEL ON PACKAGING: Ⓞ
 - FOR IR REFLOW PROCESS.
 - DATE : YYMMDD-
 - PACKAGING : TAPE & REEL.



| | | | | |
|-----|-------------|-----|------------------------|--|
| Pin | Signal NAME | QTY | MATERIAL | PLATING & COLOR |
| 1 | VBUS | 5 | 8mm*4mm | YELLOW |
| 2 | D- | 5 | COPPER ALLOY T=0.20 | GOLD FLASH ON MATING AREA, MATTE Sn 120min ON SOLDERING AREA, 60min NICKEL UNDER PLATING OVERALL |
| 3 | D+ | 4 | COPPER ALLOY T=0.20 | NICKEL 60uin MIN |
| 4 | GND | 1 | STAINLESS STEEL T=0.30 | BLACK |
| 5 | StdA_SSRX- | 1 | HIGH THERMOPLASTIC | BLACK |
| 6 | StdA_SSRX+ | 1 | HIGH THERMOPLASTIC | BLACK |
| 7 | GND_DRAIN | | | |
| 8 | StdA_SSTX- | | | |
| 9 | StdA_SSTX+ | | | |

DECIMALS: X :±0.4 X :±2'
 ANGLES: X.X :±0.3 X.X :±1'
 X.XX :±0.2

| | | | |
|---------------|---------------------------|-----------|---------------------|
| TITLE | USB 3.0 REVERSE CONNECTOR | | |
| DWN | ALLEN | PART NO. | 2UB4039-900601F |
| CHKD | JAMES | SCALE 1:1 | UNIT: mm |
| APVD | BOYE | SIZE: A3 | SHEET: 1 OF 1 REV:A |
| CUSTOMER COPY | | | |

Singatron Enterprise Co., Ltd.
 信音企業股份有限公司

1 2 3 4 5 6 7 8